

## Electronic Patent Application Fee Transmittal

Application Number:	10553209			
Filing Date:	13-Oct-2005			
Title of Invention:	Resin moldings and conductive resin composition			
First Named Inventor/Applicant Name:	Takaaki Miyoshi			
Filer:	Mark J. Henry/Drew McWilliams			
Attorney Docket Number:	1806.1010			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1110</b>